2SK3124

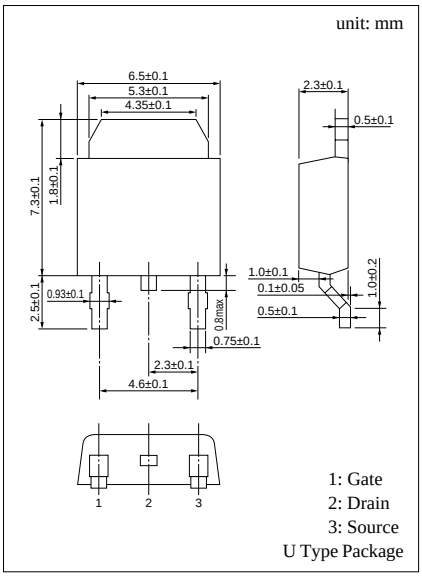
Silicon N-Channel Power F-MOS FET

■ Features

- Avalanche energy capacity guaranteed
- High-speed switching
- No secondary breakdown
- High electrostatic breakdown voltage

■ Applications

- High-speed switching (switching power supply)
- For high-frequency power amplification



■ Absolute Maximum Ratings (T_C = 25°C)

Parameter		Symbol	Ratings	Unit
Drain to Source breakdown voltage		V_{DSS}	400	V
Gate to Source voltage		V_{GSS}	±20	V
Drain current	DC	I_D	±0.5	A
	Pulse	I_{DP}	±1	A
Avalanche energy capacity		EAS*	0.25	mJ
Allowable power dissipation	T_C = 25°C	P_D	10	W
	Ta = 25°C		1	
Channel temperature		T_{ch}	150	°C
Storage temperature		T_{stg}	–55 to +150	°C

* L = 2mH, I_L = 0.5A, 1 pulse

■ Electrical Characteristics (T_C = 25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Drain to Source cut-off current	I_{DSS}	V_{DS} = 320V, V_{GS} = 0			10	µA
Gate to Source leakage current	I_{GSS}	V_{GS} = ±20V, V_{DS} = 0			±1	µA
Drain to Source breakdown voltage	V_{DSS}	I_D = 1mA, V_{GS} = 0	400			V
Gate threshold voltage	V_{th}	V_{DS} = 10V, I_D = 1mA	1		3	V
Drain to Source ON-resistance	$R_{DS(on)}$	V_{GS} = 10V, I_D = 0.1A		17	23	Ω
Forward transfer admittance	$\|Y_{fs}\|$	V_{DS} = 10V, I_D = 0.1A	100	160		mS
Diode forward voltage	V_{DSF}	I_{DR} = 0.1A, V_{GS} = 0			–1.5	V
Input capacitance (Common Source)	C_{iss}	V_{DS} = 10V, V_{GS} = 0, f = 1MHz		48		pF
Output capacitance (Common Source)	C_{oss}			10		pF
Reverse transfer capacitance (Common Source)	C_{rss}			5		pF
Turn-on time (delay time)	$t_{d(on)}$	V_{DD} = 100V, I_D = 0.1A, V_{GS} = 10V, R_L = 1Ω		65		ns
Rise time	t_r			35		ns
Fall time	t_f			40		ns
Turn-off time (delay time)	$t_{d(off)}$			70		ns
Thermal resistance between channel and case	$R_{th(ch-c)}$				12.5	°C/W
Thermal resistance between channel and atmosphere	$R_{th(ch-a)}$				125	°C/W

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